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Tomimura, T.;

Electronics Packaging Technology Conference, 2002. 4th , 10-12 Dec. 2002

Pages:299 - 303

[Abstract] [PDF Full-Text (498 KB)] IEEE CNF

2 Void-Induced thermal impedance in power semiconductor modules: some transient temperature effects

Katsis, D.C.; van Wyk, J.D.;

Industry Applications, IEEE Transactions on , Volume: 39 , Issue: 5 , Sept.-Oct. 2003

Pages:1239 - 1246

[Abstract] [PDF Full-Text (1153 KB)] IEEE JNL

3 Natural convection enhancement of channel array in conjunction with wall surface

Yazawa, K.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2004.

ITHERM '04. The Ninth Intersociety Conference on , 1-4 June 2004

Pages:128 - 133 Vol.1

[Abstract] [PDF Full-Text (676 KB)] IEEE CNF

4 Thermal management of power electronics modules via acoustic micrography imaging

Haque, S.; Xingsheng Liu; Lu, G.-Q.; Goings, J.;

Applied Power Electronics Conference and Exposition, 2000. APEC 2000.

Fifteenth Annual IEEE , Volume: 1 , 6-10 Feb. 2000

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5 A method to predict failure of solder joints caused by thermal shock using finite element analysis for RF power amplifier applications

Yang, M.C.; Cienkus, M.; Hajovsky, M.; Basey, T.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2000.

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6 Linear Interference suppression for band-limited DS/SS communications with spectral overlapping

Joon Ho Cho; Jeong, Y.K.; Lehnert, J.S.;

MILCOM 2002. Proceedings, Volume: 1, 7-10 Oct. 2002

Pages:743 - 747 vol.1

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7 Experimental measurement and simulation of thermal performance due to aging in power semiconductor devices

Katsis, D.C.; van Wyk, J.D.;

Industry Applications Conference, 2002. 37th IAS Annual Meeting. Conference Record of the, Volume: 3, 13-18 Oct. 2002

Pages:1746 - 1751 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(1152 KB\)\]](#) IEEE CNF

8 Void induced thermal impedance in power semiconductor modules: some transient temperature effects

Katsis, D.C.; van Wyk, J.D.;

Industry Applications Conference, 2001. Thirty-Sixth IAS Annual Meeting.

Conference Record of the 2001 IEEE, Volume: 3, 30 Sept.-4 Oct. 2001

Pages:1905 - 1911 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(440 KB\)\]](#) IEEE CNF

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